

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (currently amended): An i~~Implant comprising for an intracorporal, telemetric measurement with~~  
a sensor device being fixedly connected to a first end of a longitudinal carrier; and  
an inductive coil, ~~which is connected to the sensor device via electrical connection lines being that are arranged on the a longitudinal carrier;~~ and  
a covering encapsulating, ~~by means of which~~ the sensor device, the carrier with the connection lines and the coil ~~are encapsulated;~~  
**characterized in that**  
wherein the carrier (3) for the electrical connection lines (4) comprises such~~has a sufficient~~ a rigidity such that the sensor device (1) ~~which is fixedly bonded to one carrier end,~~ is adapted to be guided by ~~means of the carrier during implantation to the target position and held in position at the target position, and that the covering part (6) encapsulating the coil (2) is provided~~has means for providing a subcutaneous fastening.
2. (currently amended): The i~~Implant according to claim 1, wherein~~  
**characterized in that**  
the carrier (3) is arranged at in an angle  $<180^{\circ}$ , ~~especially from 60° to 120°~~ relative to the plane, in which the coil windings (8) of the inductive coil (2) are arranged.
3. (currently amended): The i~~Implant according to claim 1 or 2, wherein~~  
**characterized in that**  
~~at the carrier (3) there are provided two connection lines (4) between the coil (2) and the sensor device (1).~~
4. (currently amended): The i~~Implant according to one of the claims 1 to 3, wherein~~  
**characterized in that**  
the carrier (3) ~~is formed in a flat manner.~~

5. (currently amended): The iMplant according to ~~one of the claims 1 to 4~~, further comprising  
**characterized in that**  
~~in the covering part (9) with which the carrier (3) and the electrical connection lines (4) being arranged on the carrier (3) are encapsulated there is provided a stiffening foil or an armoring being provided in the covering part.~~
6. (currently amended): The iMplant according to ~~one of the claims 1 to 5~~, wherein  
**characterized in that**  
the carrier (3) is formed as at least one of a rod and or a foil.
7. (currently amended): The iMplant according to ~~one of the claims 1 to 6~~, wherein  
**characterized in that**  
the carrier (3) is formed as a stiffened foil, ~~especially by camber or as carrier with at least one of a rectangular or and a circle-segment-like cross-section.~~
8. (currently amended): The iMplant according to ~~one of the claims 1 to 7~~ 1, wherein  
**characterized in that**  
a frame is fastened at the first end of the carrier (3) there is fastened a frame (10) in which, -the sensor device (1) is arranged positively fitting fits within the frame.
9. (currently amended): The iMplant according to claim 8, wherein  
**characterized in that**  
the frame (10) is formed one piece with the carrier (3).
10. (currently amended): The iMplant according to ~~one of the claims 1 to 9~~, wherein  
**characterized in that**  
the carrier (3) is formed as a common carrier for the electrical connection lines (4) and the coil windings (8).

11. (currently amended): The iMplant according to one of the claims 1 to 10, wherein  
**characterized in that**  
the sensor device (1) comprises at least one pressure sensor.
12. (currently amended): The iMplant according to one of the claims 1 to 11, wherein  
**characterized in that**  
the covering part (6) encapsulating the coil (2) is adapted provided for a  
subcutaneous, especially epidural, positioning of the coil, wherein the sensor device has to be  
arranged in an interior of the brain.
13. (currently amended): The iMplant according to claim 11 or 12, wherein  
**characterized in that**  
the encapsulating material of the covering part (7) covering the sensor device (1) is  
formed as a pressure transmitting medium, especially of silicon.
14. (currently amended): The iMplant according to one of the claims 1 to 13,  
**characterized by**  
its formation as intracranial measurement device, wherein the sensor device (1) is  
adapted to be positioned for at least one of an intraparenchymal and a or  
intraventricular pressure measurement.
15. (new) An implant according to claim 2, wherein the angle is from 60° to 120°.
16. (new) An implant according to claim 12, wherein the covering part encapsulating the  
coil is adapted to be arranged in the epidural.
17. (new) An implant according to claim 13, wherein the encapsulating material of the  
covering part covering the sensor device is made of silicon.